



SOT618-7

plastic thermal enhanced very thin quad flat package; no leads; 40 terminals

21 April 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN40
Package type industry code	HVQFN40
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
JEITA package outline code	- - -
Mounting method type	S (surface mount)
Issue date	5-11-2010

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		5.9	-	6	6.1	mm
E	package width		5.9	-	6	6.1	mm
A	seated height		0.8	-	0.85	1	mm
A ₂	package height		-	-	-	-	
e	nominal pitch		-	-	0.5	-	mm
n ₂	actual quantity of termination		-	-	40	-	



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2. Package outline

HVQFN40: plastic thermal enhanced very thin quad flat package; no leads;
40 terminals; body 6 x 6 x 0.85 mm

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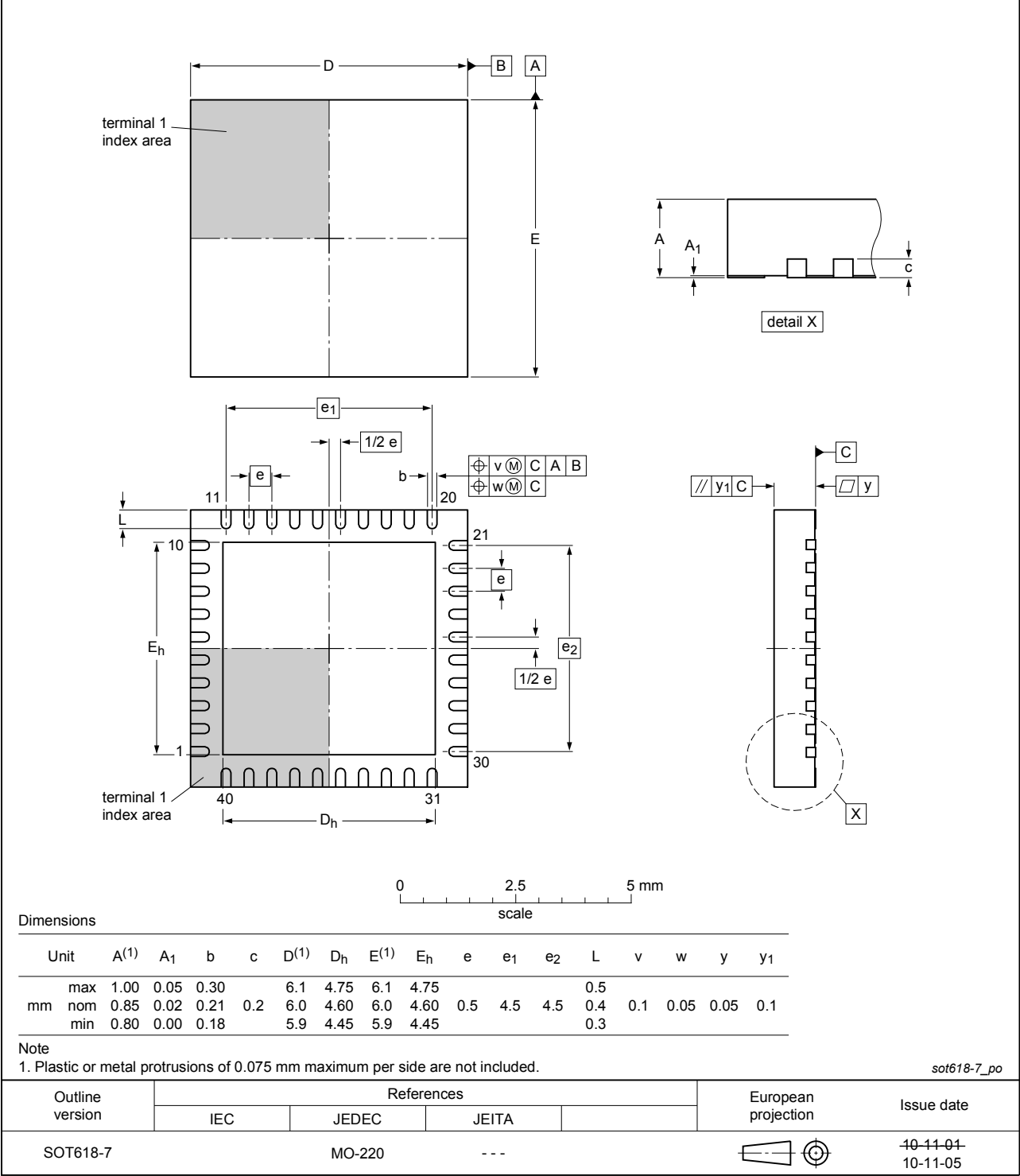


Fig. 1. Package outline HVQFN40 (SOT618-7)

3. Soldering

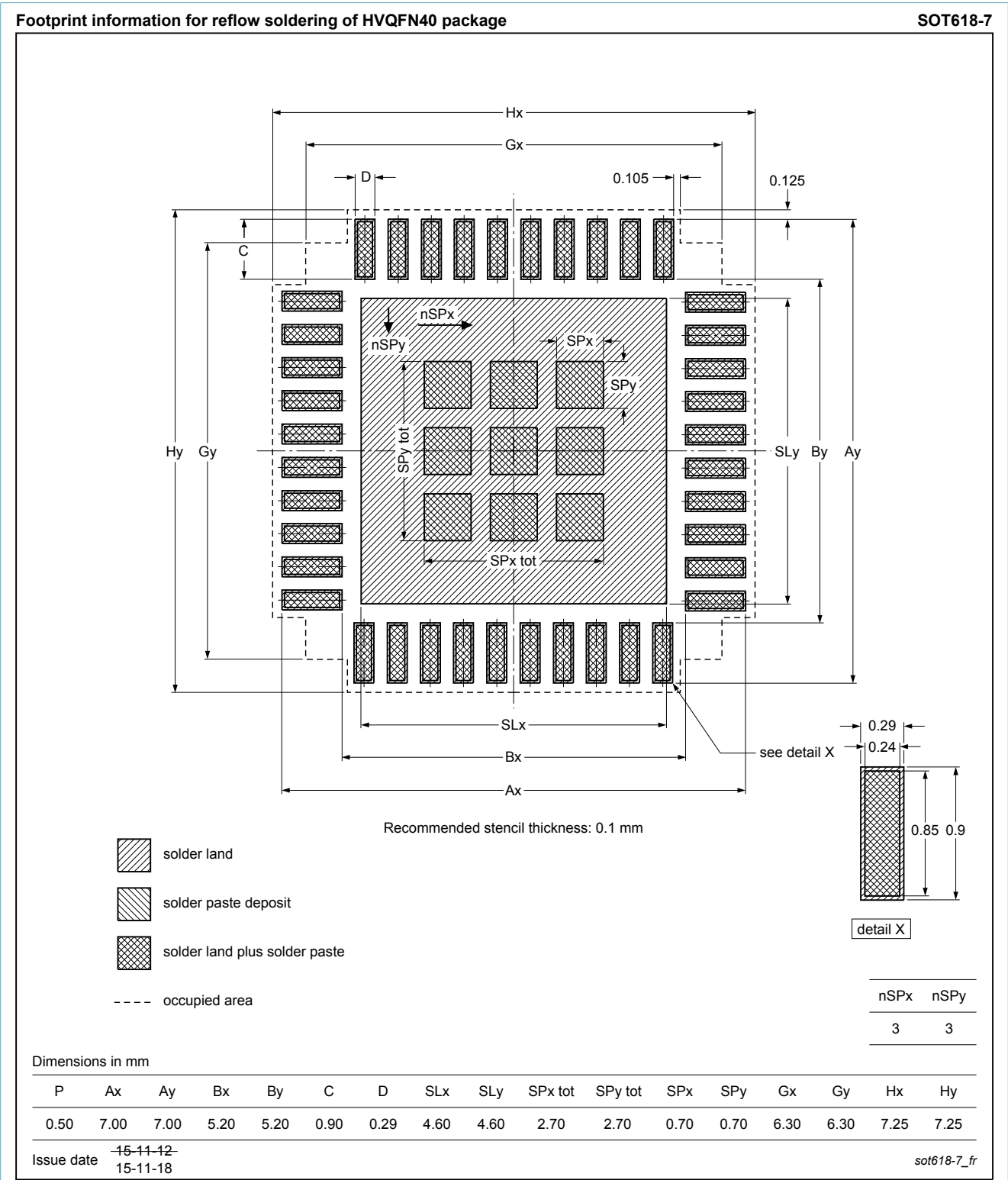


Fig. 2. Reflow soldering footprint for HVQFN40 (SOT618-7)

4. Legal information

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package; no leads; 40 terminals

5. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Soldering..... 3

4. Legal information..... 4

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